

CLAIMS

1. An electronic module for a chip card with contactless operation, said module
5 including a first substrate (S2) to which a microelectronic chip (2) is attached, and a first antenna (L3) connected to said chip and formed by a plurality of turns wound around said microelectronic chip, and said electronic module including a second substrate (S1) superimposed on the first substrate (S2) and provided with a recess (17) positioned in such a way that said microelectronic chip (2) is positioned in said recess, wherein said second
10 substrate of the electronic module includes a second antenna (L2) and a third antenna (L1) that are connected in series, and wherein the turns of said second antenna (L2) and of said third antenna (L1) of the electronic module are distributed on either side of the second substrate (S1) of the electronic module, and wherein at least some of the turns of the second and third antennas (L2, L1) situated on either side of the second substrate (S1) of the
15 electronic module are positioned facing one another, so as to create a capacitance between the two planes of turns of the second and third antennas of the electronic module.

2. The electronic module as claimed in claim 1, characterized in that the first antenna (L3) is electrically insulated from the second and third antennae (L2, L1) by
20 interposition of an insulating film (14).

3. The electronic module as claimed in any one of claims 1 or 2, characterized in that the second and third antennae (L2, L1) are electrically connected to the first antenna (L3) by way of a conductive adhesive (18).
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4. The electronic module as claimed in either one of claims 1 and 2, characterized in that an insulating foil (14) is interposed between the first and second substrates (S2, S1) and in that the third antenna (L1) is electrically connected to the first antenna (L3) by way of a connecting wire (19).
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5. The electronic module as claimed in any one of the preceding claims, characterized in that the overall thickness of the two substrates (S1, S2) is smaller than the thickness of the module.

6. The electronic module as claimed in any one of the preceding claims, characterized in that the upper face of the second substrate (S1) is substantially at the same level as the upper face of the chip (2).
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7. A chip card, characterized in that it includes an electronic module as claimed in any one of claims 1 to 6.